TOSHIBA Field Effect Transistor with Built-in Schottky Barrier Diode

Silicon N-Channel MOS Type (U-MOS V-H)

TPCA8A04-H

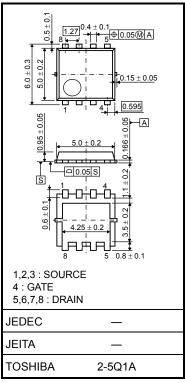
High Efficiency DC-DC Converter Applications
Notebook PC Applications
Portable Equipment Applications

- Built-in a schottky barrier diode Low forward voltage: $V_{DSF} = 0.6 \text{ V (Max)}$
- High-speed switching
- Small gate charge: QSW = 13.4 nC (typ.)
- Low drain-source ON-resistance: RDS (ON) = 2.3 m Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 127 \text{ S (typ.)}$
- Low leakage current: $IDSS = 100 \mu A (max) (VDS = 30 V)$
- Enhancement mode: $V_{th} = 1.3 \text{ to } 2.3 \text{ V } (V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

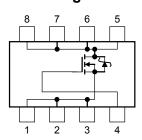
Characte	eristic	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	30	V	
Drain-gate voltage (R	$k_{GS} = 20 \text{ k}\Omega$)	V_{DGR}	30	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	ID	44	Α	
Drain current	Pulsed (Note 1)	I _{DP}	132	A	
Drain power dissipati	on (Tc=25°C)	P_{D}	45	W	
Drain power dissipati	on $(t = 10 s)$ (Note 2a)	P_{D}	2.8	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	P _D	1.6	W	
Single-pulse avalance	ne energy (Note 3)	EAS	252	mJ	
Avalanche current		I _{AR}	44	А	
Repetitive avalanche	energy c=25°C) (Note 4)	E _{AR}	3.32	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature	range	T _{stg}	-55 to 150	°C	

Unit: mm



Weight: 0.069 g (typ.)

Circuit Configuration



Note: For Notes 1 to 4, refer to the next page.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

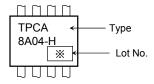
This transistor is an electrostatic-sensitive device. Handle with care.



Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case (Tc=25°C)	R _{th (ch-c)}	2.78	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	44.6	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	78.1	°C/W

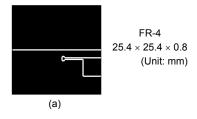
Marking (Note 5)

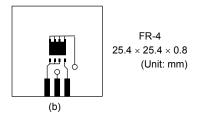


Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)

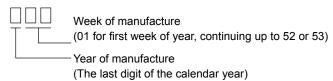




Note 3: VDD = 24 V, Tch = 25°C (initial), L = 0.1 mH, RG = 25 $\Omega,$ IAR = 44 A

Note 4: Repetitive rating: pulse width limited by maximum channel temperature

Note 5: * Weekly code: (Three digits)



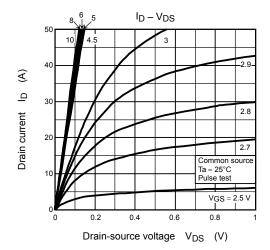


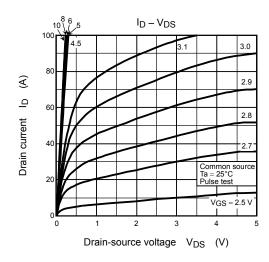
Electrical Characteristics (Ta = 25°C)

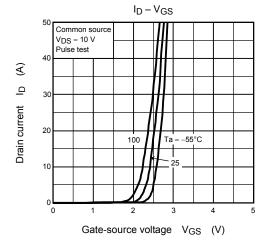
Cr	Characteristic		Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±100	nA
Drain cutoff curre	ent	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	_	_	100	μА
Drain course bro	akdown voltago	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	30	_	_	V
Drain-source breakdown voltage		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	15	_	_	v
Gate threshold v	oltage	V _{th}	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	1.3	_	2.3	V
Drain-source ON	rosistanco	Pro (OVI)	$V_{GS} = 4.5 \text{ V}, I_D = 22 \text{ A}$	_	2.9	4.1	mΩ
Diain-source ON	-resistance	R _{DS} (ON)	$V_{GS} = 10 \text{ V}, I_D = 22 \text{ A}$	_	— 2.3 3.2 64 127 — — 4400 5700		1112.2
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 22 \text{ A}$	64	127	_	S
Input capacitano	е	C _{iss}		_	4400	5700	pF
Reverse transfer	capacitance	C _{rss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	180	270	
Output capacitar	ice	C _{oss}		_	990	_	
Gate resistance		rg	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 5 \text{ MHz}$	_	1.0	1.5	Ω
Switching time	Rise time	t _r	ACS 10 A 10 = 55 Y 10 = 55 Y 10 A 10	_	4.9	_	ns ns
	Turn-on time	t _{on}			15	_	
	Fall time	t _f			8.3	_	
	Turn-off time	t _{off}	$V_{DD} \stackrel{-}{\approx} 15 \text{ V}$ Duty \leq 1%, $t_W = 10 \mu\text{s}$	_	57	_	
Total gate charge	Total gate charge (gate-source plus gate-drain)		$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 44 \text{ A}$	_	59	_	
			$V_{DD} \approx 24 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 44 \text{ A}$	_	30	_	
Gate-source charge 1		Q _{gs1}	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 44 \text{ A}$		13	_	nC
Gate-drain ("Miller") charge		Q _{gd}		_	7.0	_	_
Gate switch charge		Q _{SW}		_	13.4		

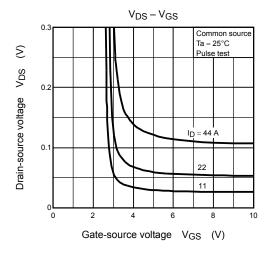
Source-Drain Ratings and Characteristics (Ta = 25°C)

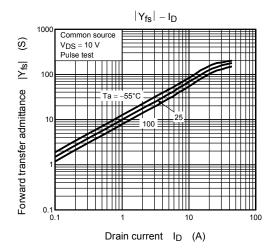
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit	
Peak forward current	Pulse	(Note 1)	I _{FP}	_	_	_	132	Α
Forward voltage (diode)		V_{DSF}	I _{DR} = 1 A, V _{GS} = 0 V	_	- 0.4	- 0.6	V	
			I _{DR} = 44 A, V _{GS} = 0 V	_	_	- 1.2	٧	

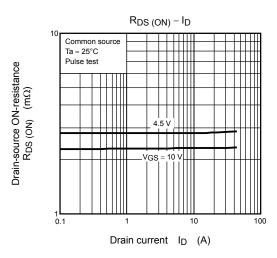


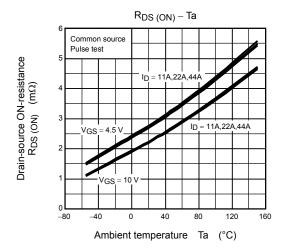


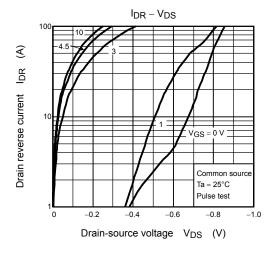


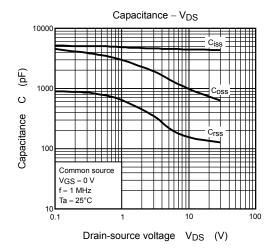


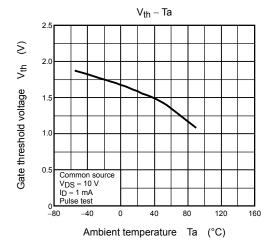


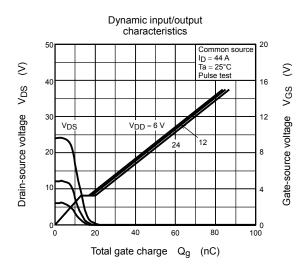


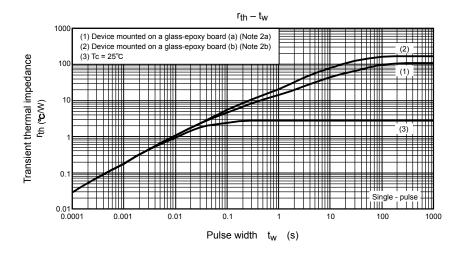


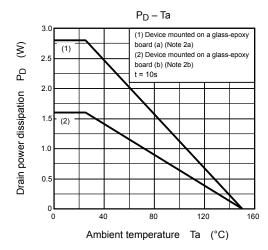


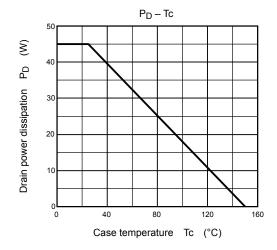


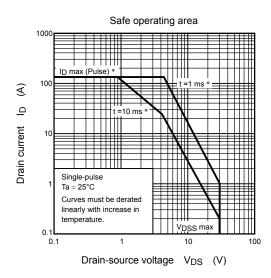


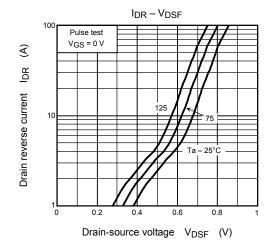


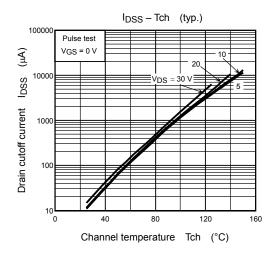


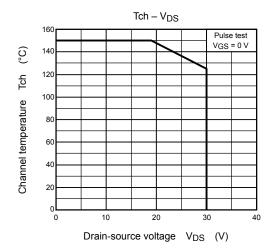












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20070701-EN GENERAL

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